ROYALOHM

SPECIFICATION FOR APPROVAL

TRELIK COMERCIAL IMPORTADORA LTD.

Description: Thick Film Chip Resistors (Terminal Lead Free)

Royalohm Part no.: 0201WMFxxxxTCE (RMC 1/20W (0201) +/-1%)

Approved by

Parts corresponding to RoHS Compliant: 2005-Apr.-1

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Approved	Checked	Prepared	
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Issued Date: 2011/10/20

	CHANGE NOTIFICATION HISTORY						
Version	Date of Version	History	Remark				
1	2011/10/20	Resistance range: $10\Omega \sim 1M\Omega$					
+							
+							
+							
		1					

Customer: TRELIK COMERCIAL IMPORTADORA LTD. Part. No.: 0201WMFxxxxTCE

1. Scope:

This specification for approval relates to Thick Film Chip Resistors (Terminal Lead Free) manufactured by ROYALOHM 's specifications.

2. Type designation:

The type designation shall be in the following form:

Ex.

Type	Power Rating	Resistance tolerance	Nominal Resistance
RMC 0201	0.05W (1/20W)	F	510Ω

3. Ratings:

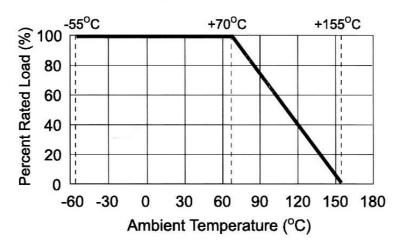
Туре	RMC 0201
Power Rating	0.05W (1/20W)
Max. Working Voltage	25 V
Max. Overload Voltage	50 V
Temperature Range	-55°C∼+155°C
Ambient Temperature	70 °C

3.1 Power rating:

Resistors shall have a power rating based on continuous load operation at an ambient temperature of 70 $^{\circ}\!C$. For temperature in excess of 70 $^{\circ}\!C$, The load shall be derate as shown in figure 1.

Figure 1

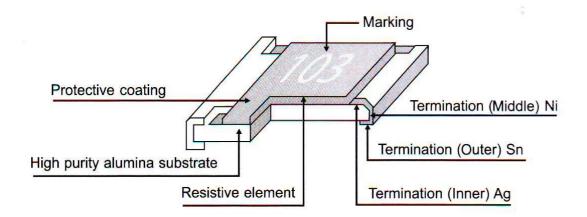
Derating Curve



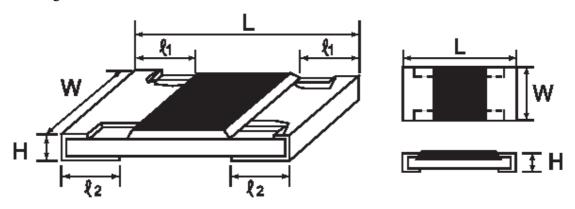
3.2 Nominal Resistance

Effective figures of nominal resistance shall be in accordance with E-24 and E-96 series E-96 series for 1 % and E-24 series for 2 % and 5 %

4. Construction:



5. Power rating and dimensions



Dimension:

	Dimension (mm)						
Туре	$L \pm 0.03$	$W \pm 0.03$	$H \pm 0.03$	$\ell 1 \pm 0.05$	$\ell 2 \pm 0.05$		
RMC 0201	0.60	0.30	0.23	0.10	0.15		

Power Rating:

Туре	Power Rating at 70 °C	Tolerance %	Resistance Range	Standard Series
RMC 0201	0.05W (1/20W)	± 1	$10\Omega \sim 1M\Omega$	E-96

- 6. Marking:
 - 6.1 Resistors
 - A. Chip Resistors type 0201 No marking
 - 6.2 Labels

Label shall be marked with the following item:

- A. Nominal Resistance and Resistance Tolerance
- B. Power Rating and Size
- C. Quantity
- D. Part No.
- E. P.O.No.
- F. Lot No.

Ex.

ROYALOHM

CHIP RESISTOR

RESISTANCE: 510 Ω \pm 1 % WATTAGE: 1/20W SIZE: 0201

QUANTITY: 10,000 PCS Pb-Free

PART NO.:

P.O.NO.:

LOT NO.: 6050008 0201WMF5100TCE

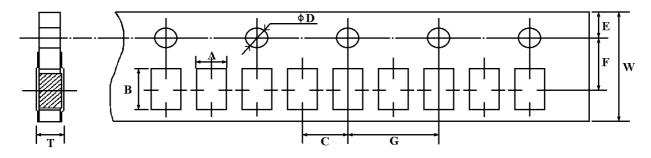
	Thick Film Chip Resist	ors (Terminal Lead Free)
7. Performano	ce specification:	
Characteristics	Limits	Test Methods
Characteristics	Limits	(JIS C 5201-1)
Insulation	$1,000~\mathrm{M}\Omega$ or more	Apply 500V DC between protective coating
resistance		and termination for 1 min, then measure
		(Sub-clause 4.6)
Dielectric	No evidence of flashover	Apply 500V AC between protective coating
withstanding	mechanical damage, arcing or	and termination for 1 minute
voltage	insulation break down	(Sub-clause 4.7)
		Natural resistance change per temp.
		degree centigrade.
		R2-R1
Temperature	10Ω : $\pm 400 \text{ PPM/}^{\circ}\text{C}$	\sim x 10 ⁶ (PPM/°C)
coefficient	$>10\Omega$: $\pm 200 \text{ PPM/}^{\circ}\text{C}$	$R_1(t_2-t_1)$
		R1: Resistance value at room temperature (t1)
		R ₂ : Resistance value at room temp. plus 100 °C (t2)
		(Sub-clause 4.8)
Short time	Resistance change rate is	Permanent resistance change after the
overload	$\pm (1.0\% + 0.1\Omega)$ Max.	application of a potential of 2.5 times RCWV
		for 5 seconds
		(Sub-clause 4.13)
		Test temperature of solder : 245 \pm 3 $^{\circ}$ C
Solderability	95 % coverage Min.	Dwell time in solder : $2 \sim 3$ seconds
		(Sub-clause 4.17)
Soldering temp.	Electrical characteristics shall be	Wave soldering condition: (2 cycles Max.) Pre-heat: $100 \sim 120 ^{\circ}\text{C}$, $30 \pm 5 \text{sec}$.
reference	satisfied. Without distinct	Suggestion solder temp.: $235 \sim 255$ °C, 10 sec. (Max.)
reference	deformation in appearance.	Peak temp.: 260 °C
	(95 % coverage Min.)	Reflow soldering condition: (2 cycles Max.)
		Pre-heat: $150 \sim 180 ^{\circ}\text{C}$, $90 \sim 120 \text{sec}$.
		Suggestion solder temp.: $235 \sim 255 ^{\circ}\text{C}$, $20 \sim 40 \text{sec}$.
		Peak temp.: 260 ℃
		(°C) Peak: 260°C (Max)
		250 235°C ~ 255°C
		200
		180 °CPre Heating Zone
		150 150 °C
		100 20~40 sec
		Soldering Zone
		50 Heating time
		Temperature profile for avaluation
		Hand soldering condition:
		The soldering iron tip temperature should be less than
		300°C and maximum contract time should be 5 sec.

	Thick Film Chip Resi	stors (Termin	al Lead Free)				
7. Performan	ce specification :						
Characteristics	Limits		Test Methods				
Characteristics	Limits		(JIS C 5201-1	1)			
Soldering	Resistance change rate is:	Dip the resis	tor into a solder bath h	naving			
Heat	$\pm (1\% + 0.05\Omega)$ Max.	a temperatur	e of 260°C±3°C and h	old it for 10±1			
		seconds.					
		(Sub-clause	4.18)				
			hange after continuous				
		5 cycles for o	duty cycle specified be	elow:			
		Step	Temperature	Time			
Temperature	Resistance change rate is	1	-55°C ± 3°C	30 mins			
cycling	$\pm (0.5\% + 0.05\Omega)$ Max.	2	Room temp.	10∼15 mins			
		3	+155°C ± 2°C	30 mins			
		4	Room temp.	$10\sim15$ mins			
		(Sub-clause	,				
		Resistance cl	hange after 1,000 hour	S			
Load life in	Resistance change rate is	(1.5 hours "c	on", 0.5 hour "off") at	RCWV			
humidity	$\pm (1.0\% + 0.1\Omega)$ Max.	•	y chamber controlled a				
			and 90 to 95 % relative	humidity			
		(Sub-clause					
			esistance change after				
Load Life	Resistance change rate is	1 -	RCWV, with duty cyc				
	$\pm (1.0\% + 0.1\Omega)$ Max.	, in the second	(1.5 hours"on", 0.5 hour"off") at 70° C $\pm 2^{\circ}$ C ambient				
		(Sub-clause					
Terminal	Resistance change rate is		Twist of Test Board :				
bending	$\pm (1.0\% + 0.05\Omega)$ Max.		Y/X = 5/90 mm for 10 seconds				
		(Sub-clause	(Sub-clause 4.33)				

8. Packing specification:

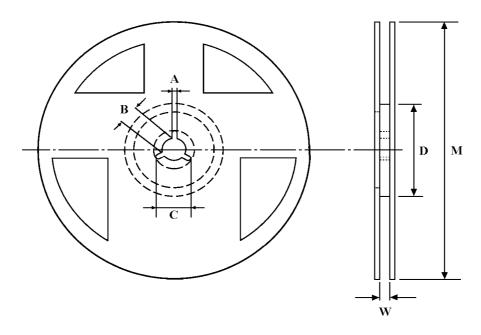
* Taping Dimension (mm)

A. Paper taping

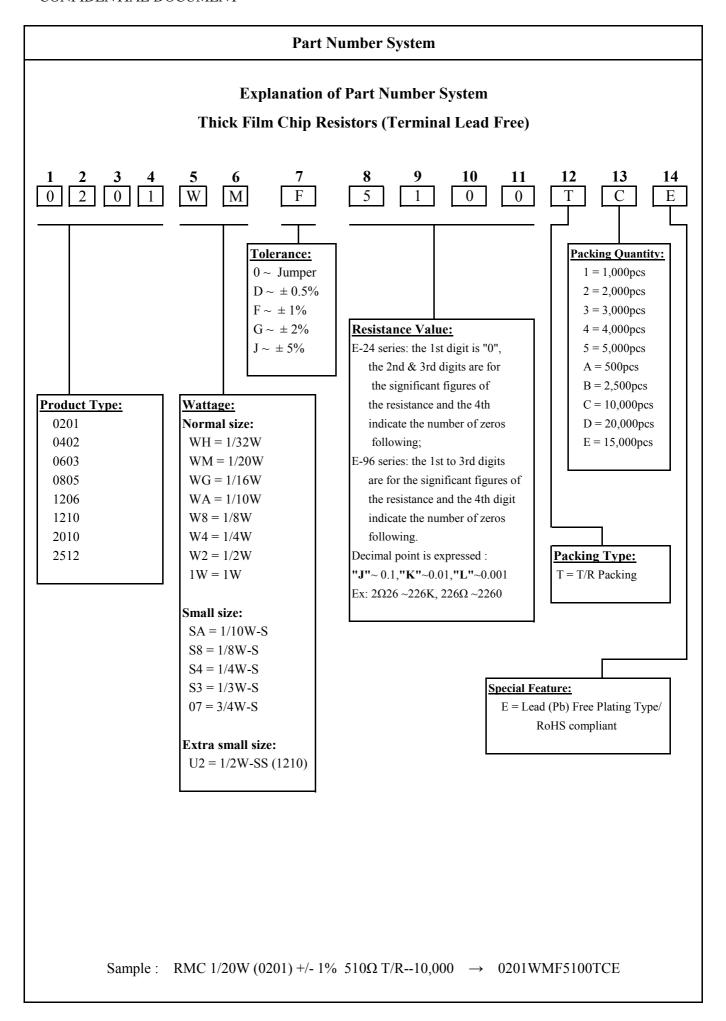


Туре	$A \pm 0.05$	B ± 0.05	$C \pm 0.05$	ØD +0.1	E ± 0.1	F ± 0.05	$G \pm 0.1$	W ± 0.2	T ± 0.1
RMC 0201	0.40	0.70	2.0	1.5	1.75	3.5	4.0	8.0	0.42

^{*} Reel Dimension (mm)



Туре	Packaging	Quantity Per Reel	$A \pm 0.5$	$B \pm 0.5$	$C \pm 0.5$	D ± 1	M ± 2	W ± 1
RMC 0201	Paper	10,000 pcs.	2	13	21	60	178	10



Environment Related Substance

This product complies to EU RoHS directive, EU PAHs directive, EU PFOS directive and Halogen free.

Ozone layer depleting substances.

Ozone depleting substances are not used in our manufacturing process of this product.

This product is not manufactured using Chloro fluorocarbons (CFCs), Hydrochlorofluorocarbons (HCFCs), Hydrobromofluorocarbons (HBFCs) or other ozone depleting substances in any phase of the manufacturing process.

Storage Condition

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ and a relative humidity of $60\%\text{RH} \pm 10\%\text{RH}$

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

- 1. In salty air or in air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂
- 2. In direct sunlight